# XP04116 (XP4116)

## Silicon PNP epitaxial planar type

For switching/digital circuits

#### Features

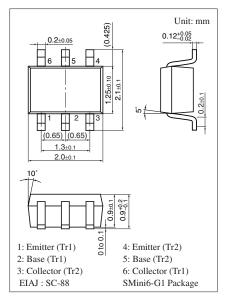
- Two elements incorporated into one package (Transistors with built-in resistor)
- Reduction of the mounting area and assembly cost by one half

#### Basic Part Number

• UNR2116 (UN2116) × 2

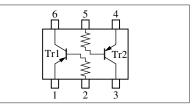
#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

| Parameter                             | Symbol           | Rating      | Unit |  |
|---------------------------------------|------------------|-------------|------|--|
| Collector-base voltage (Emitter open) | V <sub>CBO</sub> | -50         | V    |  |
| Collector-emitter voltage (Base open) | V <sub>CEO</sub> | -50         | V    |  |
| Collector current                     | I <sub>C</sub>   | -100        | mA   |  |
| Total power dissipation               | P <sub>T</sub>   | 150         | mW   |  |
| Junction temperature                  | Tj               | 150         | °C   |  |
| Storage temperature                   | T <sub>stg</sub> | -55 to +150 | °C   |  |
|                                       |                  |             |      |  |



#### Marking Symbol: 6U

#### Internal Connection



#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

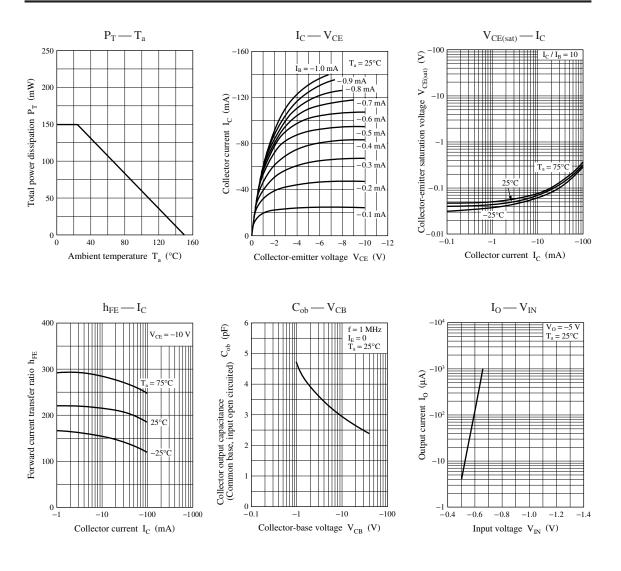
| Parameter                                    | Symbol               | Conditions   | Min  | Тур | Max    | Unit |
|--|----------------------|--|------|-----|--------|------|
| Collector-base voltage (Emitter open)        | V <sub>CBO</sub>     | $I_{C} = -10 \ \mu A, I_{E} = 0$   | -50  |     |        | V    |
| Collector-emitter voltage (Base open)        | V <sub>CEO</sub>     | $I_{\rm C} = -2 \text{ mA}, I_{\rm B} = 0$   | -50  |     |        | V    |
| Collector-base cutoff current (Emitter open) | I <sub>CBO</sub>     | $V_{CB} = -50 \text{ V}, I_E = 0$  |      |     | - 0.1  | μΑ   |
| Collector-emitter cutoff current (Base open) | I <sub>CEO</sub>     | $V_{CE} = -50 \text{ V}, I_B = 0$  |      |     | - 0.5  | μΑ   |
| Emitter-base cutoff current (Collector open) | I <sub>EBO</sub>     | $V_{EB} = -6 V, I_C = 0$   |      |     | - 0.01 | mA   |
| Forward current transfer ratio               | h <sub>FE</sub>      | $V_{CE} = -10 \text{ V}, I_C = -5 \text{ mA}$  | 160  |     | 460    | _    |
| Collector-emitter saturation voltage         | V <sub>CE(sat)</sub> | $I_{\rm C} = -10 \text{ mA}, I_{\rm B} = -0.3 \text{ mA}$  |      |     | - 0.25 | V    |
| Output voltage high-level                    | V <sub>OH</sub>      | $V_{CC} = -5 \text{ V}, V_B = -0.5 \text{ V}, R_L = 1 \text{ k}\Omega$                                   | -4.9 |     |        | V    |
| Output voltage low-level                     | V <sub>OL</sub>      | $V_{CC} = -5 \text{ V},  \text{V}_{\text{B}} = -2.5  \text{V},  \text{R}_{\text{L}} = 1  \text{k}\Omega$ |      |     | - 0.2  | V    |
| Input resistance                             | R <sub>1</sub>       |  | -30% | 4.7 | +30%   | kΩ   |
| Transition frequency                         | f <sub>T</sub>       | $V_{CB} = -10 \text{ V}, I_E = 1 \text{ mA}, f = 200 \text{ MHz}$  |      | 80  |        | MHz  |

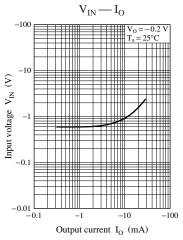
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

Note) The part number in the parenthesis shows conventional part number.

### XP04116







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